

Control of the end product into which the module will be installed

The module/s are on a PCB circuit that includes the antennae printed on the circuit.

The modules devices are designated by their nomenclature (for example U2).

The PCB is manufactured by given Gerber files that are a given and are controlled in our documentation system.

The schematics show the electrical relationship between the components.

The circuit is assembled in a SMT machine automatically. For the placement of the devices on the circuit there are X-Y coordinates that are programmed into the SMT placement machine. These coordinates assure the components are in their designed location. After programming there is a first pilot that is checked by R&D to see all the devices are in the correct placement.

There is a stage of checking the SMT oven profile is correct

The quality of soldering is checked by AOI (automatic optical inspection machine).

There is a process to glue the outside label to the printed circuit assembly and then a process to glue the whole MMI (display) to the housing of the power supply.

All is performed under a quality system accredited ISO 9001-2008.

There is a BLE communication check and for RF the frequency is checked by a Spectrum analyzer to see it is communicating at the required frequency.

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Signature:

